

## Microchip IoT Solutions Considerations for Embedded Internet of Things Designs

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## **IoT - The Internet of Things**

### Total installed base of Connected Devices

- Computers, Tablets, Smartphones, Embedded Devices etc.
- Expected to be >200billion by 2020\*

### Of this

~30billion are connected things\*

### But what is a thing....

- Autonomous sensors, actuators, systems, devices
- M2M Communications
- Collecting data
- Responding to conditions

## In short, an embedded system...

 ...with significant consideration for the effects and implications of connectivity and security



## **IoT - The Internet of Things**

### From an embedded engineers perspective

- It takes what we have provided for many years as stand alone systems, and adds connectivity, security and infrastructure
- Connectivity is migrating to wireless
- Infrastructure is moving to Cloud based systems
  - > leveraging smart devices and internet infrastructure
- HMI is moving to smart devices
- This changes how users interact with systems
- Affects business models for installation, support, servicing etc.



### What does the IoT do for us?

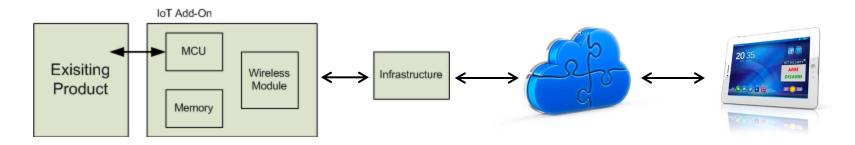
- Commission using Smart Devices
- Remote Access and Control
- Profile and Status monitoring
- Remote Diagnosis
- Field Updates
- Data Collection
- Alerts, Warnings and Updates



## Getting IoT Ready Bolt-On OR New Design

### Add IoT capability to known good product

- Product has existing comms interface, protocol and command set
- No new commands or functions needed
- Simple upgrade to make device IoT capable
- May not benefit from all features e.g. Updates
- Intention is
  - Minimal changes to current design
  - Short design cycle

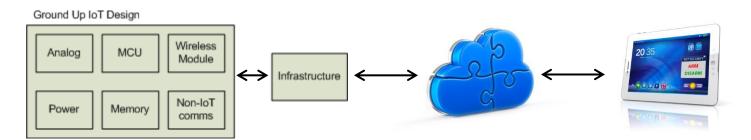




## Getting IoT Ready Bolt-On OR New Design

### Ground Up Design of Product to IoT enable

- Benefit from recent technology
- Full ground up functionality for IoT
- Longer design cycle –v- improved cost
- Design in security and robustness features
  - Class B system integrity checks
- Robust bootloaders
  - Multiple Images stored in serial flash
  - Dual Panel, Live Update capability on MCU
- Comms designs become software biased
  - Hardware design is crucial but largely a 'normal' embedded design
  - Needs greater memory resource to handle increased software complexity
  - IoT functionality leverages security and comms in software





## **Getting IoT Ready** Security Considerations



### Security is a Primary Design Consideration

- You are connecting a device to the internet...
- Assume you are a target is a good starting point
- Use standards based cryptography
  - AES-128 or better, SSL/TLS
  - Strong Key management
- Leverage infrastructure security
  - WPA2, Secure Simple Pairing etc.
- Write robust application code
  - Test for common issues, Unit testing etc.
  - Buffer Overflows, Bounds checking values, error handling



## **Getting IoT Ready** Functional Considerations

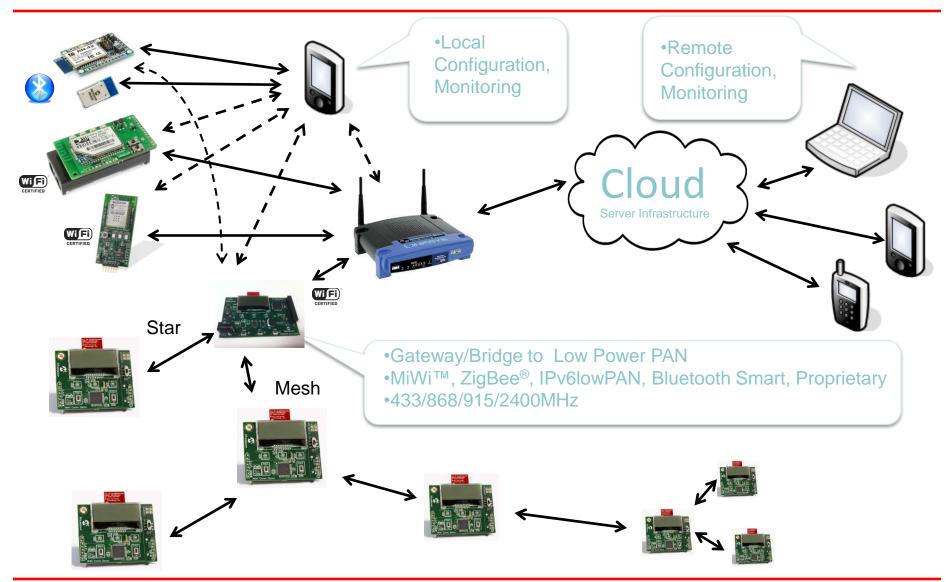


### Robustness is a Primary Design Consideration

- You're device is remote and engineer visits are expensive
- Need ability to autonomously recover from faults
  - · Creating a brick should be avoided
- Reliable, Secure bootloader employed
- Consider local bulk storage for bootload images
  - Add >2x Maximum MCU flash size as NV Storage
    - Provides space for multiple images of MCU flash
    - Can keep Last Known Good, Next New, Recovery etc. images
    - Consider 'Recovery Image'
      - Minimum functionality to connect to a secure recovery server in case of corruption or disaster recovery
    - Separate Bootload from Secure Download
      - Images held locally
      - · Can be integrity checked with server
      - Could be stored locally in encrypted format (additional memory!!)
- Test, Test and Test again...
  - 'Normal' embedded design testing needs to be supplemented with Comms and Security testing



# **Embedded Wireless System Options**





## So what is the Cloud?





- What Does it do for me?
- How does it affect me?



## So what is the Cloud?



### In simplistic terms it is client server computing

- Historically the server would be owned by and reside within the owners property
- Cloud computing moves the server side services to an off-site location and moves to greater reliance on comms. infrastructure
  - Generally servers are real or virtual and within a large non-descript location
  - Lots of physical security measures
  - Usually use latest fault tolerant and redundancy technology

### But how does that benefit me and my company?

- Low cost of ownership
  - No capital outlay and cost write down on the books
- Scalable
  - Need more resources, simply add more
  - No need to plan ahead for capital requisition, raise PO, wait for product to arrive, install maintain and pay off capital
- Redundancy
  - Data and services can be replicated in multiple locations



## So what is the Cloud?



### And how does it affect me?

- Moves a historically embedded, hardware oriented design into the murky worlds of IT, Comms, App and Web development
- Security becomes a primary embedded design consideration
- Need to interface with IT and Software professionals
- Marketing input and decisions on usability, Look and Feel, branding etc.



## Business Concerns Wireless Costs

### To add wireless:

- RF Design expertise
  - Not Digital, Not Analog, It's RF!



- Expensive RF Lab equipment
  - Spectrum Analyzers, Signal Generators, Faraday Cage
- Increased Manufacturing Complexity
  - RF Calibration and Test Equipment
- Agency Regulations
  - FCC, ETSI, IC, KCC, Telec
- Standards Body Compliance
  - BT SiG, Wi-Fi.org, Zigbee.org



- Time to Market
  - Additional expertise, equipment and regulatory factors MAY increase time to market

Microchip's GOAL: Make it Easy!



## Microchip loT Solution Building Blocks

#### **Embedded Products**

- Microcontrollers
- Memory
- Analog





#### Firmware and Software Stacks

- TCP/IP
- Bluetooth
- Wi-Fi



- MiWi™ (Lightweight Communications)
- WiFly (Serial Interface)
- SSL/TLS Security
- AES 128/256



### **Wireless and Ethernet**

- •Wi-Fi® Modules
- •Bluetooth® Modules
- Ethernet Solutions
- •CDMA/GSM









### **Cloud Solutions/Partners**

- Microchip Cloud Image
- Third Party Cloud Providers









## MPLAB® Harmony Architecture

### **Application Layer**

- Implements the overall desired behavior
- No direct HW access enables easy porting across Microchip parts

### **Common System Services**

- Manages shared resource modules to avoid conflicts.
- Provides common functionality to avoid duplication

#### **Middleware**

- Implements complex libraries & protocols (USB, TCP/IP, Graphics etc)
- Provides highly abstracted application program interface

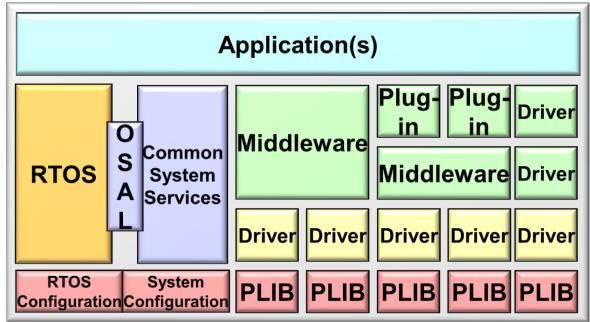
#### **Device Drivers**

- Provides simple & abstracted interface to peripheral
- Manages peripheral access control to avoid conflicts

### **Peripheral Libraries (PLIB)**

- Access library that provides low level direct access to a peripheral
- Provides common functional interface for MCHP cross micro compatibility







## **Embedded IoT Security**WolfSSL and CyaSSL

### WolfSSL

 Provide SSL/TLS solutions targeted at small memory footprint embedded systems

## CyaSSL

- Is the 3<sup>rd</sup> party SSL library developed by wolfSSL
- Integrates easily into MPLAB Harmony
- Features
  - Supports upto TLS 1.2, DTLS 1.2
  - Supports variety of Ciphers and PKI capabilities
  - Small footprint 20 -100kB Flash, 1-36kB RAM
  - 20x smaller than OpenSSL
  - Clear Licence GPLv2/Commercial





## The Cloud "Stack"









Software as a Service (SaaS)



Platform as a Service (PaaS)





Infrastructure as a Service (Most Flexible and Scalable)
(IaaS)







### You Want the Best of Both Worlds

- Ease of development of SaaS without the cost or Lock-In
- Availability and Scalability of laaS plus the get-off-the-ground ease of SaaS
- Low cost of entry
- Ease of quick prototype



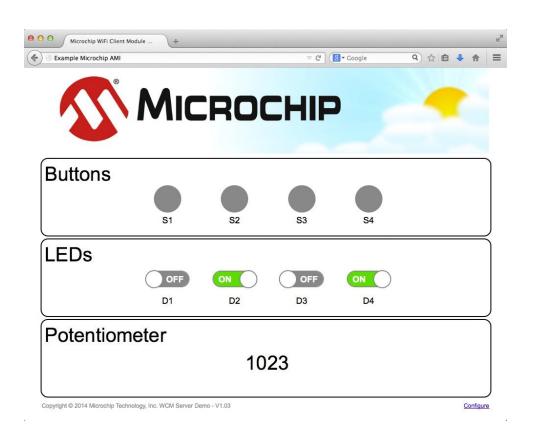
## Microchip and Amazon AWS

- Amazon provide
  - Massive, cost effective, scalable infrastructure and services
- Microchip has created a server image that is available at Amazon for <u>free</u>
  - Linux, Apache, PHP, MySQL
  - Preconfigured to work as a web-based compliment to the WCM Demo Kit
- Microchip works directly with Amazon's AWS staff to provide solutions that can be deployed with Microchip embedded hardware and Amazon servers
  - Solution = Client hardware + Pre-configured Server image as a hybrid SaaS + PaaS + IaaS.
  - Low cost of entry
  - Quick to prototype with complete software/firmware transparency





## **WCM** Development Kit 1

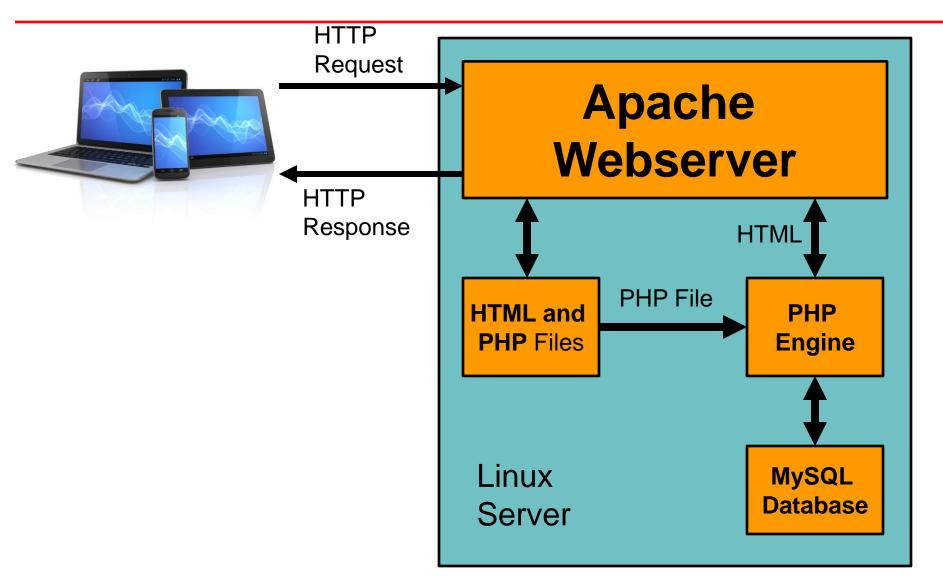




## WCM Development Kit 1 (DM182020)

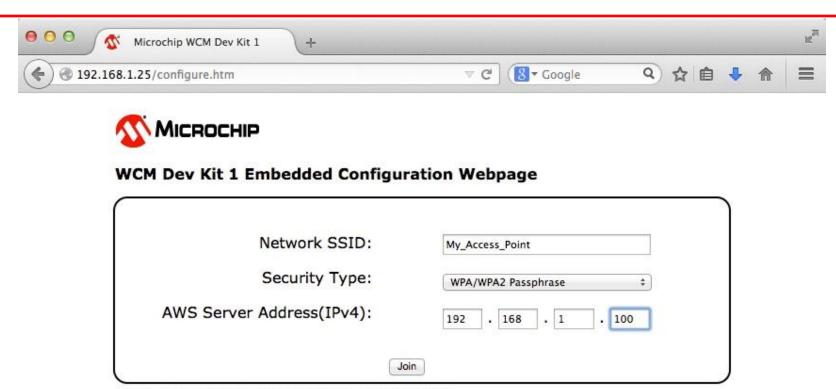


## How it works as a platform





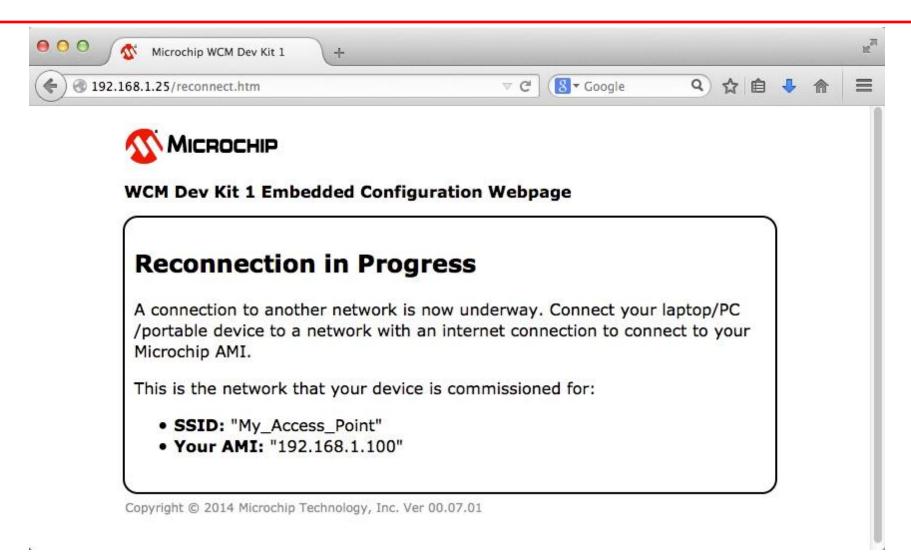
## **Enter AP / EC2 Info**



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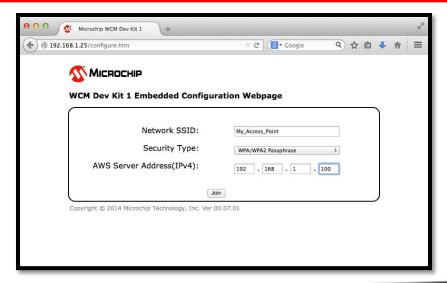


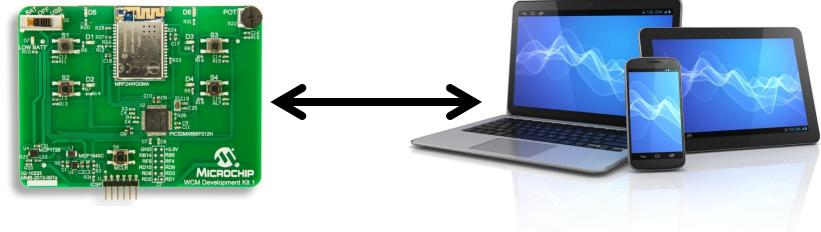
## Reconnection





# How We Commission WCM Development Kit 1



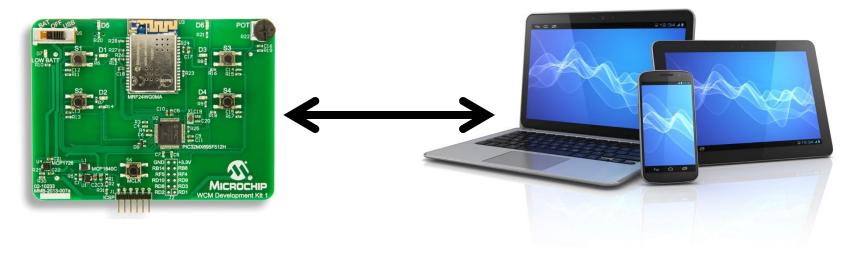




## Soft AP Mode

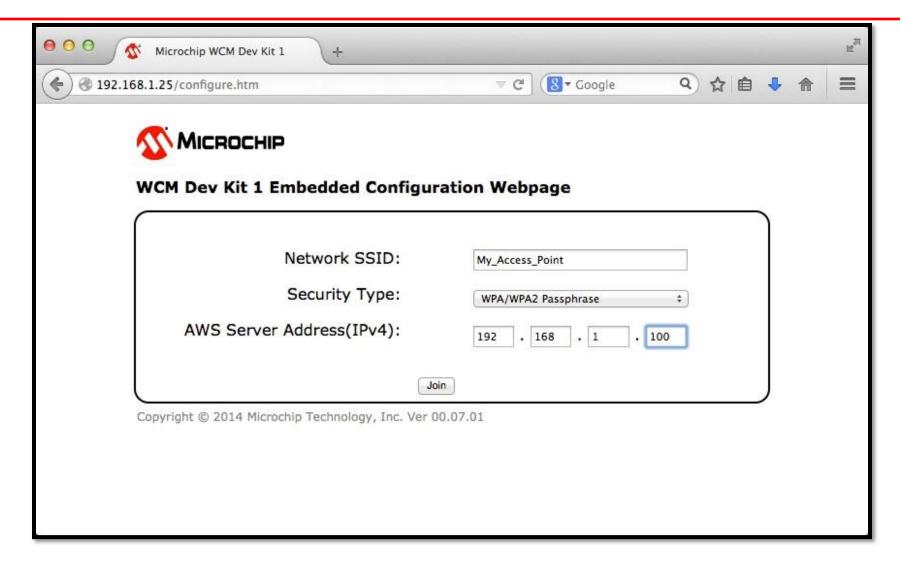
 Allows device to become centralized coordinator for network (like an Access Point)

SSID: WCM\_Soft\_AP\_XXXX



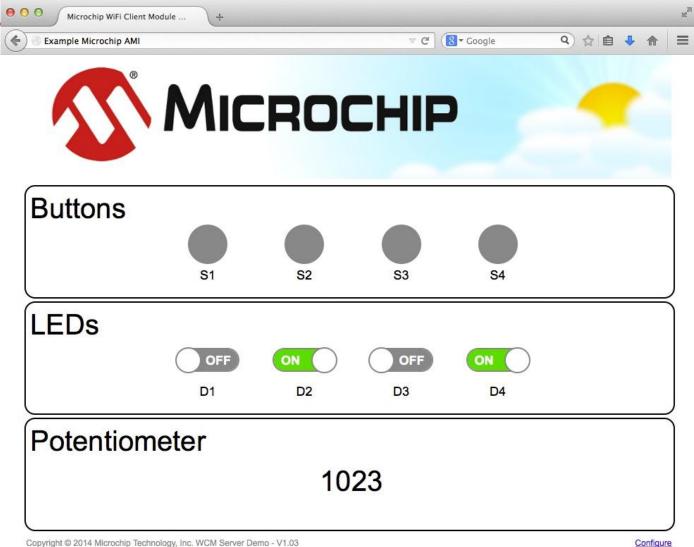


## **Configuration Webpage**





## Webpage





## **Summary**

### The Future is in Embedded IoT

- Advancing technologies in wireless
- Lower power and lower cost solutions
- The Internet of Things is changing the embedded world
- Smart devices and cloud connectivity create new opportunities
- Multiple wireless solutions for a given application
- Microchip provide complete solutions

# 30 Billion Connected Things by 2020



## **Any Questions?**





## **Thank You**



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